

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	leu near chuen-rong.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:46
L2	135	lin near charles.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:47
L3	3339	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:47
L4	1251	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:47
L5	1553	438/118.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:47
L6	1047	438/125.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:47
L7	296	438/611.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:48
L8	1479	438/613.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:48
L9	443	438/617.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:48

EAST Search History

L10	23	(metal near base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:55
L11	19	(metal near base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace) and (mechanical\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:59
L12	15	(metal near base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace) and (mechanical\$3) and (etch\$3 near3 metal near base).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:57
L13	2	(metal near base) and (etch\$3 near mask) and (pillar near5 embed\$3) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace) and (mechanical\$3) and (etch\$3 near3 metal near base).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:59
L14	4	(metal near base) and (etch\$3 near mask) and (pillar near5 embed\$3) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace) and (mechanical\$3) and (etch\$3 near3 metal near base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 15:59

EAST Search History

L15	29	(metal near base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace) and (mechanical\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:00
L16	29	(metal near base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:00
L17	34	(base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (connection near3 joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:01
L18	34	(base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (joint\$3) and (routing near line) and (pad) and (conduct\$3 near trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:01
L19	34	(base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (joint\$3) and (routing near line) and (conduct\$3 near trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:01
L20	36	(base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (joint\$3) and (routing) and (conduct\$3 near trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:02
L21	36	(base) and (etch\$3 near mask) and (pillar) and (chip component device ic integrated near circuit) and (encapsul\$3) and (joint\$3) and (routing) and (trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:02
L22	46	(base) and (etch\$3 near mask) and (chip component device ic integrated near circuit) and (encapsul\$3) and (joint\$3) and (routing) and (trace)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:04

EAST Search History

L23	333	"5353498" "5668405" "5856212" "6038133" "6359235" "6492587" "6538210" "6774467"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:06
L24	825	"4955523" "4970571" "4984358" "5074947" "5106461" "5116463" "5137845" "5167992" "5196371" "5209817" "5237130" "5260234" "5261593"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:08
L25	855	"5275330" "5284796" "5293067" "5327010" "5334804" "5346750" "5355283" "5358621" "5397921" "5407864" "5424245" "5438477" "5439162"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:09
L26	611	"5447886" "5454161" "5454928" "5475236" "5477933" "5487007" "5483421" "5484647" "5487218" "5489804" "5493096" "5508229" "5525065"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:11
L27	238	"5536973" "5547740" "55568105564181" "5572069" "5576052" "5599744" "5611140" "5611884"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/22 16:11